SN75ALS193...D, J OR N PACKAGE (TOP VIEW)

1B [

1A П

1Y 👖

GII 4

2A 🛛 6

2B [] 7 GND [] 8

2

3

2Y 🛚 5

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16 VCC

15 **1** 4B

14 **1** 4A

13 4Y

12 G

11 3Y

10 3A

9[] 3B

- Meets or Exceeds ANSI Standard EIA/TIA-422-B and EIA/TIA-423-A and ITU Recommendations V.10 and V.11
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- 3-State Outputs
- Common-Mode Input Voltage Range -7 V to 7 V
- Input Sensitivity . . . ±200 mV
- Input Hysteresis . . . 120 mV Typ
- High Input Impedance . . . 12 k Ω Min
- Operates from Single 5-V Supply
- Low Supply Current Requirement 35 mA Max
- Improved Speed and Power Version of the AM26LS32A

description

The SN75ALS193 is a monolithic quadruple line receiver with 3-state outputs designed using advanced low-power Schottky technology. This technology provides combined improvements in bar design, tooling production, and wafer fabrication. This, in turn, provides significantly lower power requirements and permits much higher data throughput than other designs. This device meets the specifications of ANSI Standards EIA/TIA-422-B and EIA/TIA-423-A and ITU Recommendations V.10 and V.11. It features 3-state outputs that permit direct connection to a bus-organized system with a fail-safe design that ensures the outputs will always be high if the inputs are open.

The device is optimized for balanced multipoint bus transmission at rates up to 20 megabits per second. The input features high input impedance, input hysteresis for increased noise immunity, and an input sensitivity of \pm 200 mV over a common-mode input voltage range of -7 to 7 V. It also features active-high and active-low enable functions that are common to the four channels. The SN75ALS193 is designed for optimum performance when used with the 'ALS192 quadruple differential line driver.

The SN75ALS193 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each receiver)									
DIFFERENTIAL INPUTS	ENA	BLES	OUTPUT						
A – B	G	G	Y						
$V_{ID} \ge 0.2 V$	H	X	H						
	X	L	H						
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	H	X	?						
	X	L	?						
$V_{ID} \leq -0.2 V$	H	X	L						
	X	L	L						
Х	L	Н	Z						
Open	H	X	H						
	X	L	H						

H = high level, L = low level, X = irrelevant, ? = indeterminate,

Z = high impedance (off)



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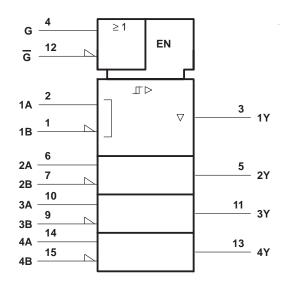


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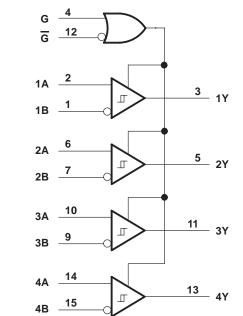
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logic symbol[†]

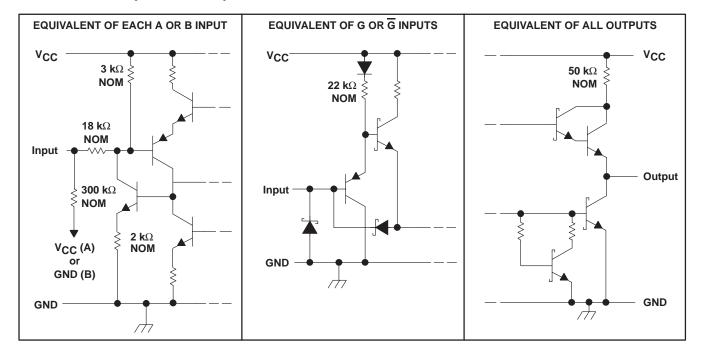


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs



logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1) Input voltage, V _I (A or B)	±15 V
Differential input voltage, VID (see Note 2)	±15 V
Enable input voltage, V ₁	
Low-level output current, I _{OL}	50 mA
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	

[†] Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditons is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.

2. Differential-input voltage is measured at the noninverting input with respect to the corresponding inverting input.

_	DISSIPATION RATING TABLE								
	PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING					
	J	1025 mW	8.2 mW/°C	656 mW					
	Ν	1150 mW	9.2 mW/°C	736 mW					

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
Common-mode input voltage, VIC			±7	V
Differential input voltage, VID			±12	V
High-level input voltage, VIH	2			V
Low-level input voltage, VIL			0.8	V
High-level output current, I _{OH}			-400	μA
Low-level output current, IOL			16	mA
Operating free-air temperature, T _A	0		70	°C



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electrical characteristics over recommended range of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST C	TEST CONDITIONS [†]			MAX	UNIT
VIT+	Positive-going input threshold voltage					200	mV
V _{IT} –	Negative-going input threshold voltage			-200§			mV
V _{hys}	Hysteresis voltage (V _{IT+} –V _{IT} –)				120		mV
VIK	Enable-input clamp voltage	V _{CC} = MIN,	l _l = – 18 mA			-1.5	V
Vон	High-level output voltage	$V_{CC} = MIN,$ $I_{OH} = -400 \ \mu A,$	V _{ID} = 200 mV, See Figure 1	2.5	3.6		V
\/-·		$V_{CC} = MIN,$	I _{OL} = 8 mA			0.45	v
VOL Lo	Low-level output voltage	$V_{ID} = -200 \text{ mV},$ See Figure 1	I _{OL} = 16 mA			0.5	
IOZ	High-impedance-state output current	V _{CC} = MAX	V _O = 2.4 V			20	A
			V _O = 0.4 V			-20	μA
łı	Line input current	Other input at 0,	V _{CC} = MIN, V _I = 15 V		0.7	1.2	
		See Note 3	$V_{CC} = MIN,$ $V_{I} = -15 V$		-1.0	-1.7	mA
			V _{IH} = 2.7 V			20	
lΗ	High-level enable-input current	V _{CC} = MAX	VIH = MAX			100	μA
۱ _{IL}	Low-level enable-input current	V _{CC} = MAX,	V _{IL} = 0.4 V			-100	μΑ
	Input resistance			12	18		kΩ
los	Short-circuit output current	$V_{CC} = MAX,$ $V_{O} = 0,$	V _{ID} = 3 V, See Note 4	-15	-78	-130	mA
ICC	Supply current	V _{CC} = MAX,	Outputs disabled		22	35	mA

[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

§ The algebraic convention, in which the less positive limit is designated minimum, is used in this data sheet for threshold voltage levels only.
 NOTES: 3. Refer to ANSI Standard EIA/TIA-422-B and EIA/TIA-423-A for exact conditions.

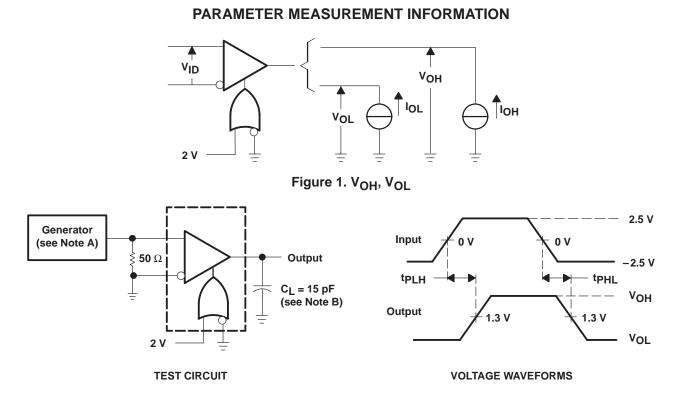
4. Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output	$V_{ID} = -2.5 V \text{ to } 2.5 V,$		15	22	
^t PHL	Propagation delay time, high-to-low-level output	$C_L = 15 \text{ pF},$ See Figure 2		15	22	
^t PZH	Output enable time to high level	C ₁ = 15 pF, See Figure 3		13	25	-
^t PZL	Output enable time to low level	C _L = 15 pF, See Figure 3		11	25	ns
^t PHZ	Output disable time from high level			13	25	
t _{PLZ}	Output disable time from low level	C _L = 5 pF, See Figure 3		15	22	



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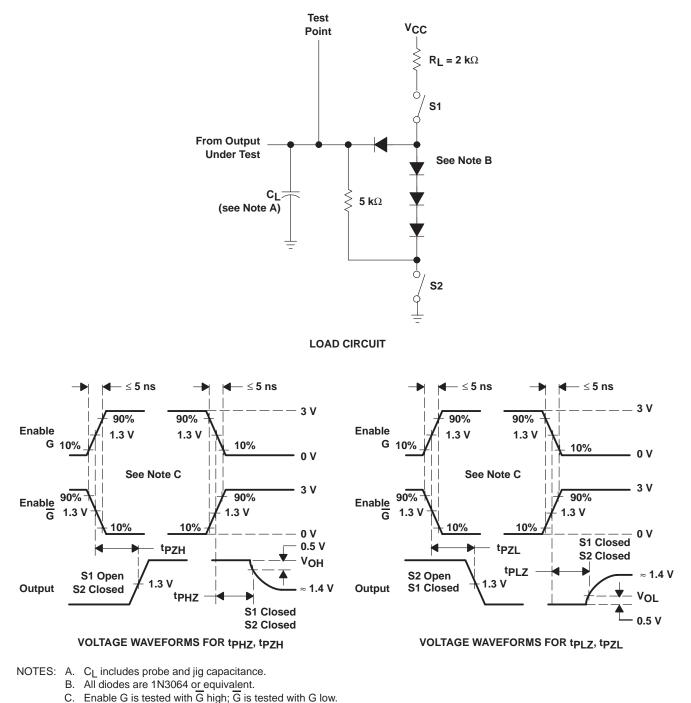


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, Z_O = 50 Ω , t_f \leq 6 ns, t_f \leq 6 ns.
 - B. CL includes probe and jig capacitance.

Figure 2. Test Circuit and Voltage Waveforms



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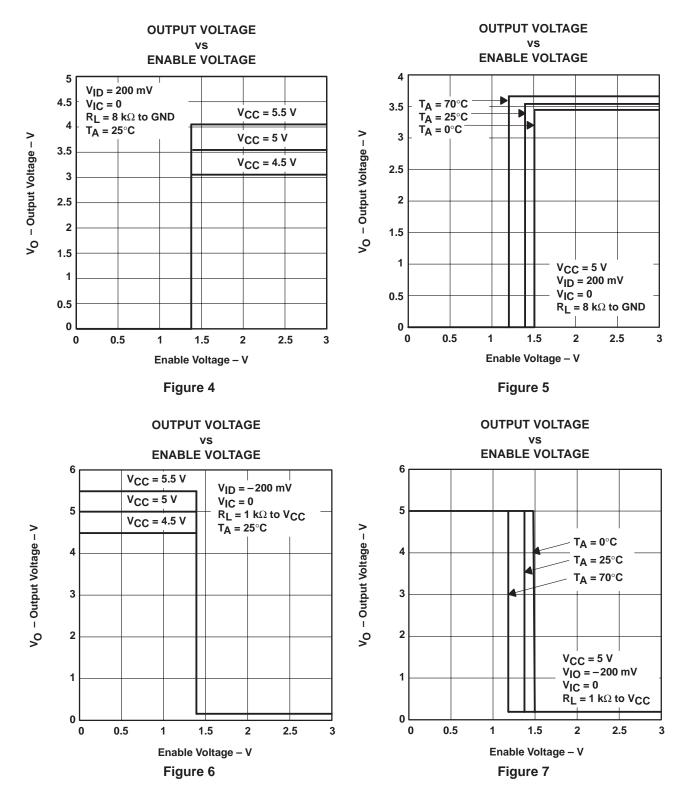


PARAMETER MEASUREMENT INFORMATION

Figure 3. Load Circuit and Voltage Waveforms

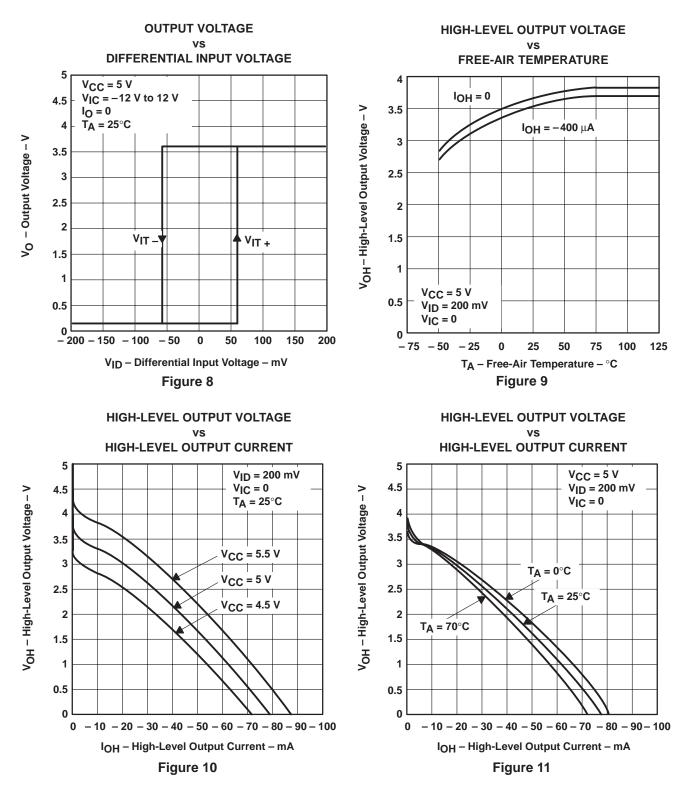


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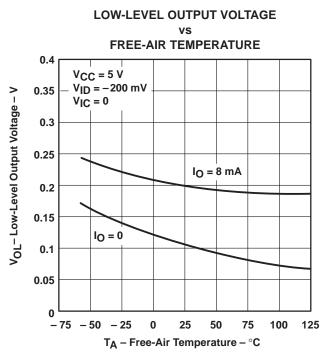


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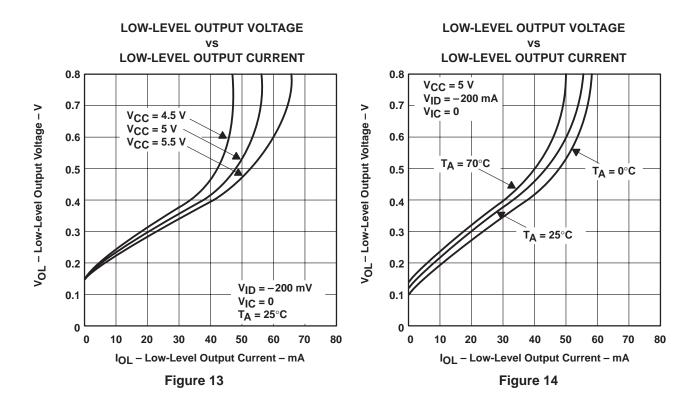




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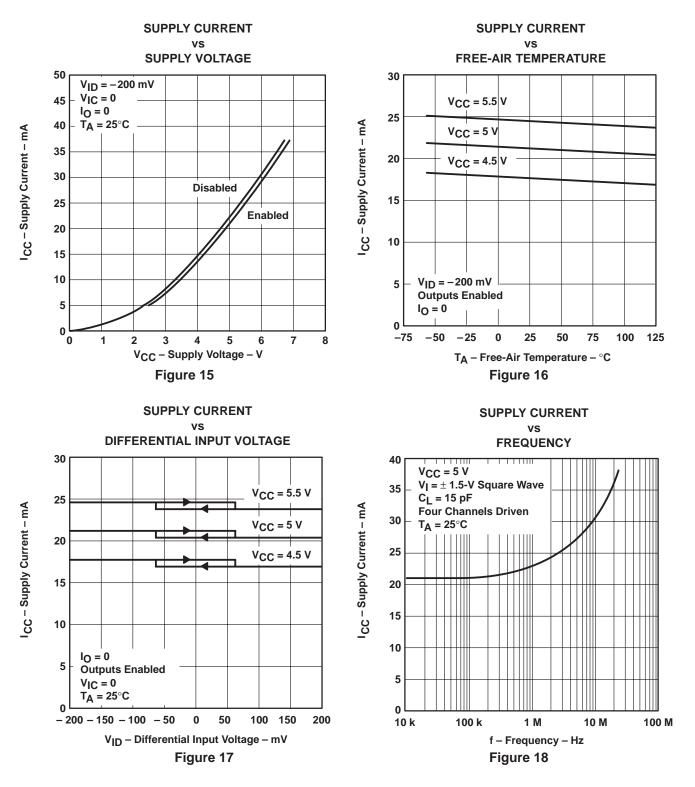






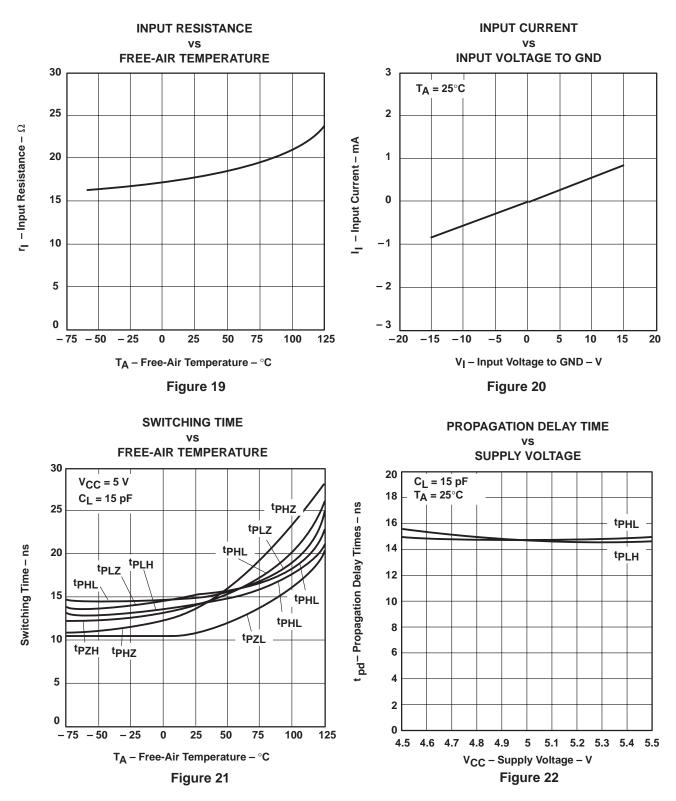


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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS193D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS193DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS193DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS193DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS193DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS193DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN75ALS193N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS193NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

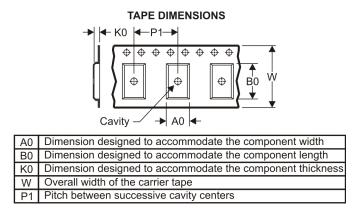
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



	Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ſ	SN75ALS193DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS193DR	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) -16x0,55 - 14x1,27 -14x1,27 16x1,95 4,80 4,80 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 Example 2,00 Solder Mask Opening

(See Note E)

NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

← 0,07 All Around

- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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